GM30

GM 30 is an anaerobic curing adhesive for the gasketing and sealing of flanges. To replaces solid gaskets, gives flexible cured films.To seal against gases, water, LPG, hydrocarbons, oils and other chemicals. Thixotropic property prevents migration of the sealant before or during curing. Shocks and vibrations resistant are unaffected properties of sealing in the range of temperature from -55 to +180°C. GM 30 is designed to be used and cured at room temperature. Where cured speed is unacceptably long, or large gaps are present, applying activator to the surface will reduce the curing within few minutes.

Technology / Base	Dimethacrylate Ester
Type of Product	Flange Sealant
Components	One Component
Curing	Anaerobic with Secondary Heat Cure or Accelerated with Activator
Appearance / Color	Red
Consistency	Thixotropic Gel

Technical Data

Property	Value	Method/Condition
Rheology		
Viscosity	1,125,000 +/- 375,000 cps @ 0.5 rpm	Brookfield at 20°C to 25°C (68°F to 77°F)
Density		
Specific Gravity	1.12	
Uncured Materials Characteristics		
Flash Point	> 93°C (200°F)	
Gap Fill	Primed-0.05 inch, Unprimed-0.01 inch	
Shelf Life	12 months unopened	
Storage Condition	20°C (68°F)	
Cured Material Characteristics		
Full Cure Conditions	24 hours at 25°C	
Cure Appearance	Red Solid	
RoHS Compliant	Yes	
Cured Mechanical Properties		
Locking Strength	Medium	
Breakaway Torque	to	
Prevailing Torque	to	
Pin/Collar Shear Strength	>725 psi	
Service Temperature	-55°C to 150°C (-65°F to 300°F)	

General Instructions

Surfaces to be bonded should be clean and dry and free of grease. Product should be applied in enough quantity to fill all engaged threads. The product performs best in thin bond gaps. Very large gaps may create gaps that will affect the cure speed and overall strength. Good contact is essential. An adequate bond develops in 15 to 45 minutes and maximum strength is attained in 24 hours. This product is not recommended for use in pure oxygen environments and/or oxygen-rich systems and should not be slected as a sealant for chlorine or other strong oxidizing materials. This product is not designed for plastics, particularly thermoplastics where stress cracking of the plastic could result. It is recommended to confirm compatibility of the product with all substrates prior to use.

### Specifications and Approvals

Curing Performance

The rate of cure will depend on environmental conditions and the substrates used. The gap of the bond line will affect set speed. Smaller gaps tend to increase set speed. Activators may be applied to further improve set speed, but may also impair overall adhesive performance.

Storage

Products should be stored unopened in a cool, dry place out of direct sunlight. Products may be refrigerated for improved shelf life, but should be brought back to room temperature before use.
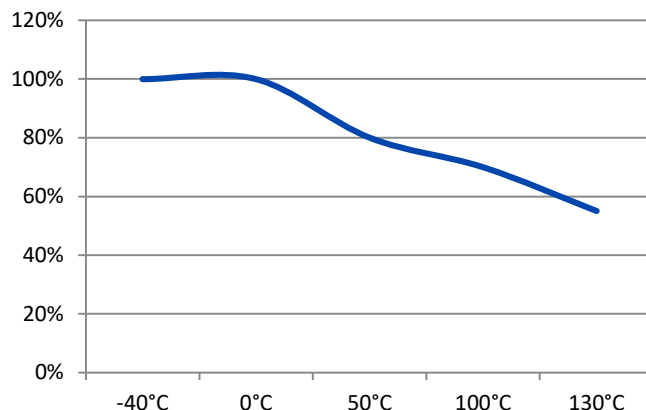
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Set Time on Various Substrates
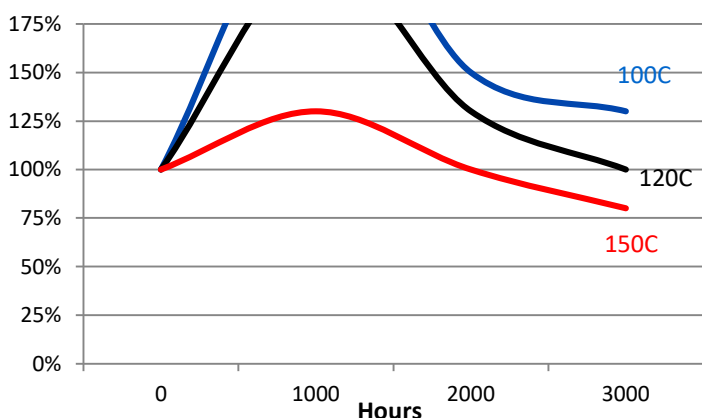
Cured at 20°C (68°F), 65% RH
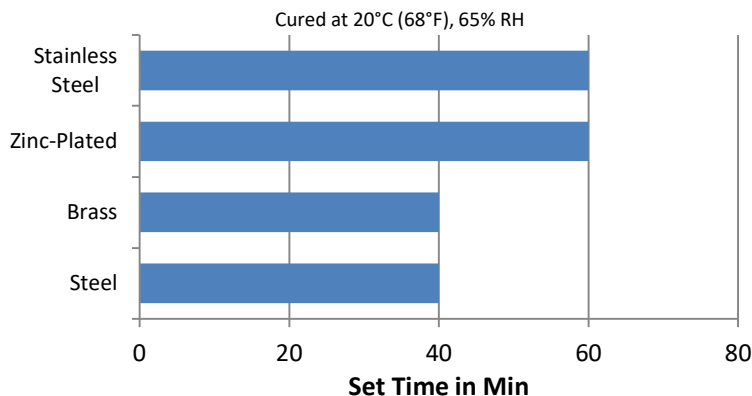
Test Conditions: 68°F / 20°C, 65% RH

Hot Strength (%RT strength, tested at temperature)

Heat Aging (aged at temp. indicated and tested @ 22°C)

Solvent Resistance

Solvent	Example	Resistance
Alcohol	Ethanol, Methanol	+ + +
Ester (aromatic)	Ethylacetate	– – –
Ketone (aromatic)	Acetone, Benzophenone	– – –
Aliphatic hydrocarbon (alkanes)	Petrol, Heptanes, Hexane	+ + –
Aromatic hydrocarbons	Benzyl, Toluol, Xylol	+ + –
Halogenated hydrocarbons	Methylenchloride, Chloroform, Chlorobenzol	– – –
Weak aqueous acid	Nitrite, muriatic acid, sulphuric acid, phosphoric acid	+ + + (– – – if concentrated)
Weak aqueous base	sodium hydroxide solution, caustic potash	+ + + (– – – if concentrated)

Safety and Disposal Advice

For safe handling information on this product, consult the Safety Data Sheet (SDS)

H.B. Fuller Company
9001 W. Fey Drive
Frankfort, IL 60423
+1.800.552.0320

www.hbfuller.com

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